

Final Product/Process Change Notification Document #: FPCN22188X

Issue Date: 19 June 2018

Title of Cha	nge:	Micro8 Assembly and Test Site Transfer.				
Proposed f	irst ship date:	26 September 2018				
Contact inf	ormation:	Contact your local ON Semiconductor Sales Office or < logic.fpcn22188x@onsemi.com >				
Samples:		Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Additional	Reliability Data:	Contact you	ır local ON Semiconductor Sales Office or <	<pre><phine.guevarra@onsemi.com></phine.guevarra@onsemi.com></pre>		
Type of not	ification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < < PCN.Support@onsemi.com >				
Change Par	Part Identification: Products with date code "U" or greater will have material listed in the table under "(new flow)".					
Change Cat	egory:	☐ Wafer Fab Change				
☐ Manu	o-Category(s): Ifacturing Site Add facturing Site Tran facturing Process	nsfer	✓ Material Change☐ Product specific change	□ Datasheet/Product Doc change✓ Shipping/Packaging/Marking□ Other:		
Sites Affected:		ON Semiconductor Sites: ON Seremban, Malaysia		External Foundry/Subcon Sites: Subcon Thailand		
Description	n and Purpose:			•		
Qualify new a	assembly and tests	site to increas	e the back end capacity.			
	Material to be	changed	Before change (existing flow)	After 90 day notification (new flow)		
	Assy Sit	e	ON Malaysia	Subcon Thailand		
	Mold Comp	ound	G600FB/G700LS	G600		
	Lead Fran	me	Ag Plated LF	PPF LF		
	Die Atta	ch	Epoxy CRM1084P	Epoxy QMI519		
	Plating	5	100% Tin	Pre plated		

TEM001793 Rev. A Page 1 of 3



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Reliability Data Summary:

QV DEVICE NAME: 7WB3125DMR2G RMS: S43460, S48165

PACKAGE: Micro 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	504hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008hrs	0/240
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
	J-STD-020 JESD-			
PC	A113	MSL 1 @ 260°C		0/720
RSH	JESD22- B106	Ta = 265C, 10 sec		0/70
SD	JSTD002	Ta = 245C, 10 sec		0/45

QV DEVICE NAME: PCA9511ADMR2G RMS: S43455, S48165

PACKAGE: Micro 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	504hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008hrs	0/240
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/238
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD- A113	MSL 1 @ 260°C		0/720
SD	JSTD002	Ta = 245C, 10 sec		0/45
RSH	JESD22- B106	Ta = 265C, 10 sec		0/70

Electrical Characteristic Summary:

Electrical characteristics Available upon request.

TEM001793 Rev. A Page 2 of 3



Final Product/Process Change Notification Document #: FPCN22188X

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List of Affected Parts:				
Part Number	Qualification Vehicle			
7WB3125DMR2G				
7WB3126DMR2G				
7WB3305DMR2G				
7WB3306DMR2G				
7WB383DMR2G	71MP24.25 DMP2.6			
7WBD3125DMR2G	7WB3125DMR2G			
7WBD3126DMR2G				
7WBD3305DMR2G				
7WBD3306DMR2G				
7WBD383DMR2G				
PCA9511ADMR2G				
PCA9517ADMR2G	PCA9511ADMR2G			
PCA9517BDMR2G	PCA9511ADMK2G			
PCA9617ADMR2G				

TEM001793 Rev. A Page 3 of 3



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
PCA9517ADMR2G		PCA9511ADMR2G
PCA9617ADMR2G		PCA9511ADMR2G